



## Material Content Data Sheet



<b>Sales Product Name</b>		IPB60R199CP		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000779562							
<b>Package</b>		PG-TO263-3-2		<b>Weight*</b>		1465.00 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	8.809	0.60	0.60	6013	6013	
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		582		
	inorganic material	phosphorus	7723-14-0	0.256	0.02		175		
	non noble metal	copper	7440-50-8	851.691	58.12	58.20	581360	582117	
wire	non noble metal	aluminium	7429-90-5	2.848	0.19	0.19	1944	1944	
encapsulation	organic material	carbon black	1333-86-4	8.786	0.60		5997		
	plastics	epoxy resin	-	96.648	6.60		65971		
	inorganic material	silicondioxide	60676-86-0	480.310	32.79	39.99	327857	399825	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6592	6592	
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156	
solder	non noble metal	tin	7440-31-5	0.098	0.01		67		
	noble metal	silver	7440-22-4	0.123	0.01		84		
	non noble metal	lead	7439-92-1	4.690	0.32	0.34	3202	3353	
*deviation	< 10%					Sum in total:	100,00		1000000

### Important Remarks:

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